



# Tin-Lead Solder Paste

## SH-6209WA

Rev. 2017/03/17 Ver. 03-01

### BASIC OVERVIEW



Sn62Pb36Ag2 Alloy  
Tin-Lead Solder Paste  
Water Soluble

### APPLICATIONS

Water Soluble Tin-Lead SMD Solder Paste  
Wide Range of Applications and PCB designs

### FEATURES

Appearance	Gray paste w/o visible foreign and clusters	
Alloy Composition	Sn62/Ag2/Pb36	JIS-Z-3282
Melting Point	179~189 °C	
Particle Size	(Type 3) +45µm < 1% , - 20µm < 10% (Type 4) +38µm < 1% , - 20µm < 10%	J-STD-005
Powder Shape	Spherical	
Flux Content	10.0 ± 1.0 wt%	JIS-Z-3197, 8.1.2
Viscosity	200 ± 30 Pa.s (25±1°C, 10rpm, Malcom)	JIS-Z-3284 Annex 6
Flux Type	ORM1	J-STD-004

### Alloy Detail Composition

(Sn)	(Pb)	(Ag)	(Cu)	(Zn)	(Al)	(Sb)	(Fe)	(As)	(Bi)	(Cd)	(Au)	(In)	(Ni)
62.0 ± 0.5	REM.	2.0 ± 0.2	0.05 MAX	0.001 MAX	0.001 MAX	0.05 MAX	0.02 MAX	0.03 MAX	0.1 MAX	0.002 MAX	0.05 MAX	0.10 MAX	0.01 MAX

(wt%)

Scan Code for Solder  
Paste Documents





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### PERFORMANCE & RELIABILITY

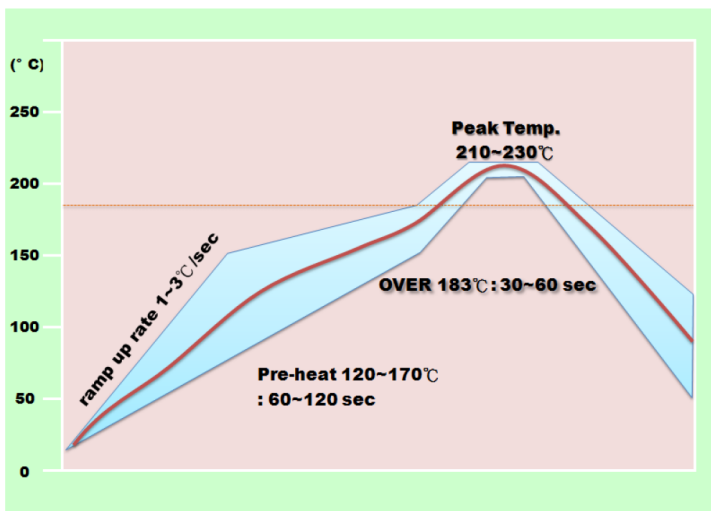
Copper Plate Corrosion Test	Pass	IPC-TM-650, 2.6.15
Spreading Test	> 90%	JIS-Z-3197, 8.3.1.1
Copper Mirror Test	Pass	IPC-TM-650, 2.3.32
Viscosity Test (25°C, 10 rpm)	200 ± 30 Pa.s	JIS-Z-3284. Annex 6
Tackiness Test (gf)	> 120 (8hr)	JIS-Z-3284. Annex 9
Slump Test	Pass	JIS-Z-3284. Annex 7,8
Solder Ball Test	Pass	JIS-Z-3284. Annex 11

S.I.R. Test	▲ Pass	IPC-TM-650, 2.6.3.3
Electro Migration Test	◆ Pass	IPC-TM-650, 2.6.14.1

▲ Test Conditions (after DI water clean): 85°C, 85% RH, 168hrs

◆ Test Conditions (after DI water clean): 65°C, 85% RH, 596hrs

### RECOMMENDED REFLOW PROFILE



Ramp Up Rate (30-150°C): 1.0-3.0 °C/sec

Pre-heating Time (120-170°C): 60-120 sec

Time Period Above 183°C: 30-60 sec

Ramp Up During Reflow: 1.0-3.0 °C/sec

Peak Temperature: 210-230 °C

Ramp Down Cooling Rate: 1.0-3.0 °C/sec

Note: The recommended reflow profile is provided as a guideline. Optimal profile may differ due to oven type, assembly layout or other process variables.



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### STORAGE & HANDLING:

- Refrigerate the solder paste at 0-10°C. Shelf life is 6 months from production date.
- Allow the paste to reach defined printing temperature (room temperature) for 3-4 hrs. Do not heat up the solder paste rapidly.
- For jars packaging, mix the solder paste before use for 1-3 mins by plastic spatula.
- It is recommended to finish fresh paste within 24 hrs. Do not store used paste and fresh paste in the same jar.
- If printing process was interrupted for more than 1 hour, remove remaining paste from stencil and seal in the jar.
- Recommended printing environment is 22-28°C and RH 30-60% .
- Flux residue is easily cleaned by 60±5°C D.I. water with minimum pressure of 60psi, and suggested to be done within 24hrs.

*Note: For more information, please refer to solder paste application guideline sheet*

### HOW TO ORDER

## SH-6209WA – T3 – 500

Solder Alloy	Flux	Particle Size	Weight / Packaging
SH-6209 = Sn62/Pb36/Ag2	WA = Water Soluble	T3 = 20-45µm T4 = 20-38µm	30 = syringe 30g 100 = syringe 100g 150 = syringe 150g 250 = plastic jar 250g 500 = plastic jar 500g 600 = small cartridge 600g 1200 = large cartridge 1200g



### CONTACTS

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